



INNOLAS
solutions



MEMBER OF
**PHOTONICS
SYSTEMS
GROUP**

INNOVATION FOR THE
NEXT GENERATION



DIVIDOS Series

LASER DEPANELING SYSTEMS
FOR THE ELECTRONIC INDUSTRY

BENEFITS

- ◆ No tooling costs and better TCO
- ◆ Full cut with 30% more panels on board
- ◆ High edge quality and less residuals on board
- ◆ No carbonization and very residuals on board
- ◆ Cutting of any shape compared to mechanical cut
- ◆ Cost effective design
- ◆ Simple and easy to maintain
- ◆ Dedicated solution for PCB depaneling
- ◆ Industry 4.0 ready

OPTIONS

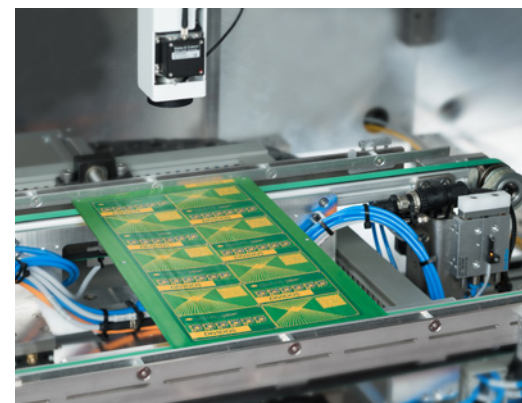
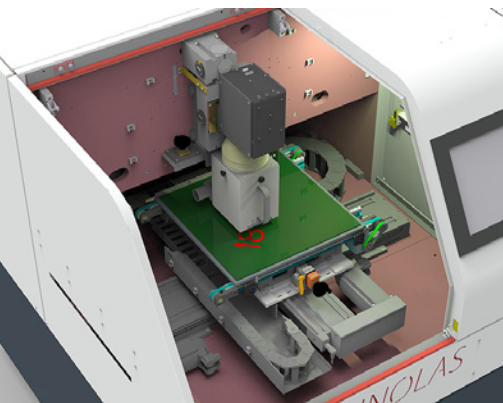
- ◆ 2nd process head (galvo scanner)
- ◆ Postprocessor for CAD file transfer
- ◆ Exhaust system
- ◆ MES Interface
- ◆ Different carrier options

TECHNOLOGY

- ◆ High speed Galvo Scanner
- ◆ Automatic calibration routines
- ◆ InnoLas μ Vision
- ◆ Windows 10 IoT
- ◆ Touch display

AUTOMATION

- ◆ Fully automated system
- ◆ Stand alone system
- ◆ SMEMA complaint



APPLICATIONS

Laser Depaneling/ Laser Routing

ACCURACY

< +/-50 μ m

SUBSTRATE

Dimension up to 457 x 457 mm (18 x 18 Inches)

LASER

ns UV, ns green, ps IR

DIMENSIONS

1440x 1521 mm 1596 mm Weight: 1100 kg
(57 x 60 x 63 Inches) (Weight 2420 lbs)

